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Patent Claims:

1.-10. Canceled

11. (Currently amended) A printed circuit board (1, 1') comprising strip conductors for electronic circuits and connections for a voltage supply unit being equipped with at least one SMD-component and additional parts that are soldered in a suitable manner, said voltage supply unit being connected to at least one supplying strip conductor (2),  
wherein at least one of the supplying strip conductors (2) includes a break which is bridged in a conductive manner by means of a fuse bridge (6), said fuse bridge (6) ~~comprising~~ consisting of a basic material, the melting point of which is lower than the melting point of the material of which the strip conductors are made.
12. (Previously presented) The printed circuit board (1, 1') as claimed in claim 11, wherein the melting point of the basic material is at least as high as the melting point of the solder used for placement of the printed circuit board (1).
13. (Previously presented) The printed circuit board (1, 1') as claimed in claim 11, wherein the fuse bridge (6) fully consists of metallic material.
14. (Previously presented) The printed circuit board (1, 1') as claimed in claim 13, wherein the metallic material comprises tin or any tin alloy.
15. (Previously presented) The printed circuit board (1, 1') as claimed in claim 11, wherein the fuse bridge (6) is connected to material of the strip conductor in a conductive fashion by means of the solder used in the soldering process.
16. (Currently amended) The printed circuit board (1, 1') as claimed in claim 11, wherein the fuse bridge (6) is shaped in such a way that it can be fed to a conventional pick-and-place machine in a taped and magazined fashion ~~like a~~

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~~per se known SMD component.~~

17. (Previously presented) The printed circuit board (1, 1') as claimed in claim 11, wherein the fuse bridge (6) is manufactured by severing from a wire or a sheet-metal strip.
18. (Previously presented) The printed circuit board (1, 1') as claimed in claim 11, wherein the basic material for manufacturing the fuse bridge (6) is coated with a layer made of a material out of the group consisting of tin, any tin alloy, gold, and passivated copper.
19. (Previously presented) The printed circuit board (1, 1') as claimed in claim 11, wherein adjacent supplying strip conductors (2) are separated from each other by recesses (12).
20. (Currently amended) A method of manufacturing a printed circuit board (1, 1') comprising strip conductors for electronic circuits and connections for a voltage supply unit being equipped with at least one SMD-component and additional electronic and/or electromechanical parts that are soldered in a suitable manner, said voltage supply unit being connected to at least one supplying strip conductor (2),  
wherein at least one of the supplying strip conductors (2) includes a break which is bridged in a conductive manner by means of a fuse bridge (6), said fuse bridge (6) ~~comprising~~ consisting of a basic material, the melting point of which is lower than the melting point of the material of which the strip conductors are made.  
the method comprising the step of manufacturing the fuse bridge (6) immediately prior to placement of the printed circuit board (1, 1').